D-6	1				1	
Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	33	(438/553).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/01 14:05
S2		apparatus with (heating adj plate) with heater with frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/13 13:11
S3	59	apparatus same (heating adj plate) same heater same frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/25 10:27
S4	820	apparatus and (heating adj plate) and heater and frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/25 10:28
S5		apparatus near (heating adj plate) near heater near frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/01 14:12
S6	6	apparatus with (heating adj plate) with heater with frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/02 18:18
S7	59	apparatus same (heating adj plate) same heater same frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/13 13:11
S9	7	apparatus and (mask\$5 adj substrate) and (heating adj plate) and heater and frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/05 10:40

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S10	1	(takei.inv. and toshichika) and apparatus and (mask\$5 adj substrate) and (heating adj plate) and heater and frame	US-PGPUB; USPAT	OR	ON	2006/05/02 18:34
S11	12	(takei.inv. and toshichika) and apparatus	US-PGPUB; USPAT	OR	ON	2006/05/02 18:42
S12	3	(takei.inv. and toshichika) and apparatus and (mask\$5 adj substrate)	US-PGPUB; USPAT	OR .	ON	2006/05/02 18:42
S13	7	(apparatus or system or assembly) and (mask\$5 adj substrate) and (heating adj plate) and heater and frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/02 18:45
S14	855	apparatus and (heating adj plate) and heater and frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/05 13:41
S15	6	apparatus with (heating adj plate) with heater with frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/05 10:42
S16		apparatus same (heating adj plate) same heater same frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/05 13:37
S17	12	apparatus and (heating adj plate) and (heater near frame)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/05 13:43
S18	120	apparatus and (heating adj plate) and (heater with frame)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/05 13:44
S19	6	apparatus with (heating adj plate) with heater with frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/25 10:29

S20	59	apparatus same (heating adj plate)	US-PGPUB;	OR	ON	2006/10/25 10:27
		same heater same frame	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB			
S21	570	(apparatus and (heating adj plate) and heater and frame) and (clearance or space)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/25 10:32
S22	3	(apparatus and (heating adj plate) and heater and frame) with (clearance or space)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/25 10:28
S23	43	(apparatus and (heating adj plate) and heater and frame) same (clearance or space)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/25 10:28
S24	13	(apparatus and ((heating adj plate) near substrate) and heater and frame) and (clearance or space)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/25 10:31
S25	3	(apparatus and ((heating adj plate) near substrate) and heater and frame) and (clearance or space) and @ad<="20030210"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/25 10:32
S26	9	(apparatus and ((heating adj plate) near substrate) and heater and frame) and (clearance or space) and @ad<="20040210"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/25 10:34
S27	358	(apparatus and (heating adj plate) and heater and frame) and (clearance or space) and @ad<="20030210"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/25 10:32

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S28	7	apparatus with (heating adj plate) with heater with frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/13 13:16
S29	14	(apparatus same (heating adj plate) same heater same frame) and @ad<="20031002"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/13 13:18
S30	616	(apparatus and (heating adj plate) and heater and frame) and @ad<="20031002"	US-PGPUB; USPAT; USOÇR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/13 13:13
S32	291	(heating adj plate) and heater and frame and peripheral and @ad<="20031002"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/13 13:19
S33·	113	(apparatus same (heating adj plate) same heater same (frame or housing or support\$3)) and @ad<="20031002"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/13 13:25
S34	227	(heating adj plate) and heater and frame and peripheral and @ad<="20031002" and apparatus	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/13 13:25
S35	24	(heating adj plate) and heater and frame and peripheral and @ad<="20031002" and apparatus and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/15 08:48
S36	29	(apparatus same (heating adj plate) same heater same (frame or housing or support\$3)) and @ad<="20031002" and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/13 13:25

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S37	3	(heating adj plate) and heater and frame and peripheral and @ad<="20031002" and apparatus and wafer and overlap\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/08 15:39
S41		(("6881058") or ("6743395")).PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/16 10:35
S42	24	(heating adj plate) and heater and frame and peripheral and @ad<="20031002" and apparatus and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/08 16:19
S43	1	("5081563").PN.	USPAT	OR	OFF	2007/08/08 16:00
S44	0	(heating adj plate) and heater and (frame with gap) and peripheral and @ad<="20031002" and apparatus and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/08 16:20
S45	0	(heating adj plate) and heater and (frame near gap) and peripheral and @ad<="20031002" and apparatus and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/08 16:20
S46	3	(heating adj plate) and heater and (frame same gap) and peripheral and @ad<="20031002" and apparatus and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/08 16:20
S47	19	(heating adj plate) and heater and (frame and gap) and peripheral and @ad<="20031002" and apparatus and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/08 16:21